

Product Summary (@T_A = +25°C)

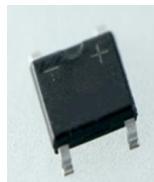
Part Number	V _{RRM} (V)	I _o (A)	V _F (V)	I _R (µA)
RABF152-13	200	1.5	1.3	5
RABF154-13	400	1.5	1.3	5
RABF156-13	600	1.5	1.3	5
RABF158-13	800	1.5	1.3	5
RABF1510-13	1000	1.5	1.3	5

Features and Benefits

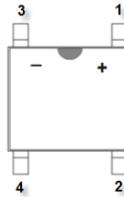
- Glass Passivated Die Construction
- Miniature Package Saves Space on PC Boards
- High Current Capability
- Fast Recovery Time for Higher Efficiency
- Ideal for SMT Manufacturing
- Low Forward Voltage Drop
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

Description and Applications

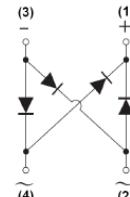
Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.



Top View



Pin Diagram



Internal Schematic

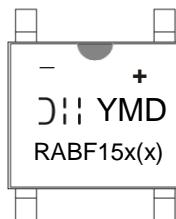
Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
RABF1510-13	Commercial	SOPA-4 (Type B)	5,000/Tape & Reel
RABF158-13	Commercial	SOPA-4 (Type B)	5,000/Tape & Reel
RABF156-13	Commercial	SOPA-4 (Type B)	5,000/Tape & Reel
RABF154-13	Commercial	SOPA-4 (Type B)	5,000/Tape & Reel
RABF152-13	Commercial	SOPA-4 (Type B)	5,000/Tape & Reel

Notes:

1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
2. See http://www.diodes.com/quality/lead_free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



RABF15x(x)= Product Type Marking Code

D11= Manufacturers' Code Marking

YMD = Date Code Marking

Y = Last Digit of Year (ex: 8 = 2018)

M = See Month/Code Table Below

D = Day 1 to 9 = 1 to 9; Day 10 to 31 = A to V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings and Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

Characteristic	Symbol	RABF152	RABF154	RABF156	RABF158	RABF1510	Unit
Peak Repetitive Reverse Voltage	V _{RRM}						
Working Peak Reverse Voltage	V _{RWM}	200	400	600	800	1000	V
DC Blocking Voltage	V _R						
RMS Reverse Voltage	V _{R(RMS)}	140	280	420	560	700	V
Average Rectified Output Current (Note 5) @ T _C = +100°C	I _O			1.5			A
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}			50			A
I ² t Rating for Fusing (1ms < t < 8.3ms)	I ² t			10.375			A ² s
Maximum Forward Voltage (Per Element) @ I _F =1.5A	V _{FM}			1.3			V
Maximum Reverse Recovery Time (Note 6)	t _{RR}	150	150	250	500	500	ns
Peak Reverse Current @ T _A = +25°C	I _R			5.0			μA
At Rated DC Blocking Voltage (Note 7) @ T _A = +125°C				200			
Typical Total Capacitance (Per Element) (Note 8)	C _T			17			ns

Thermal Characteristics

Characteristic	Symbol	Value		Unit
Typical Thermal Resistance, Junction to Ambient (Note 5) (Per Element)	R _{θJA}	80		°C/W
Typical Thermal Resistance, Junction to Lead (Per Element)	R _{θJL}	25		°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150		°C

Notes:

5. Device mounted on aluminum substrate PC board with 1.3mm² solder pad.
6. Reverse Recovery Test Conditions: I_F=0.5A, I_R=1.0A, I_{RR}=0.25A.
7. Short duration pulse test used to minimize self-heating effect.
8. Measured at 1.0MHz and applied reverse voltage of 4.0V D.C.

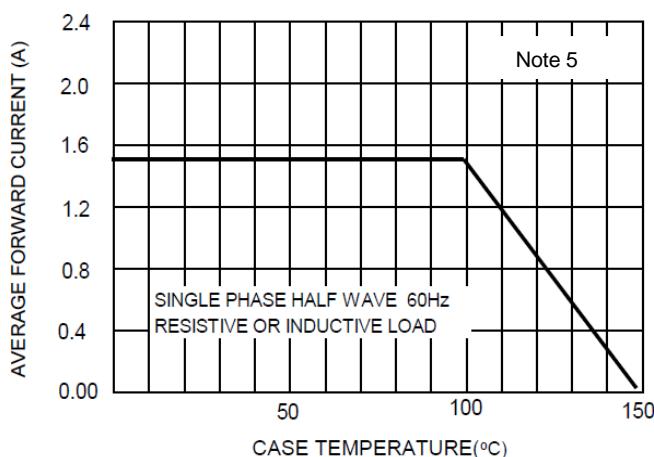


Figure 1. FORWARD CURRENT DERATING

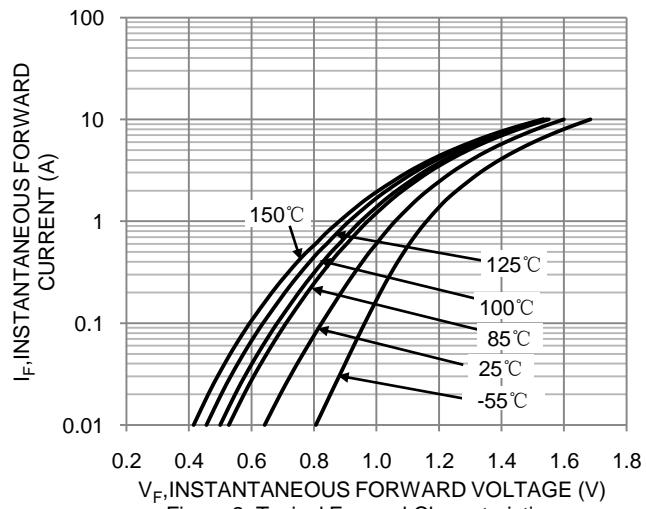


Figure 2. Typical Forward Characteristics

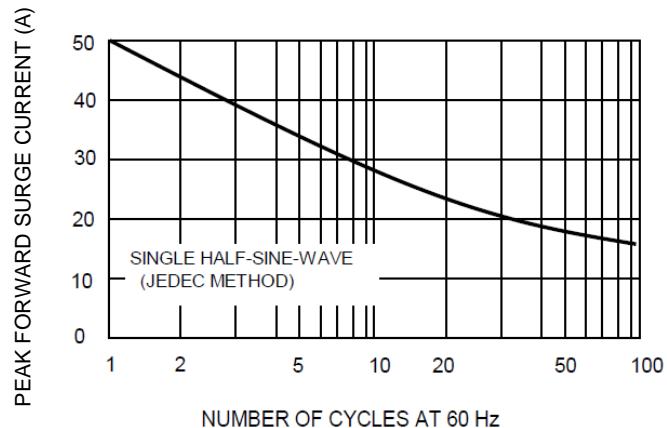


Figure 3. MAXIMUM NON-REPETITIVE SURGE CURRENT

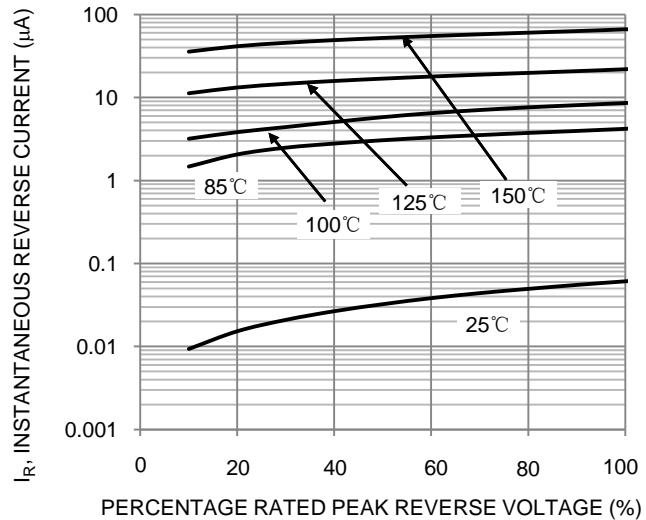


Figure 4. Typical Reverse Characteristics

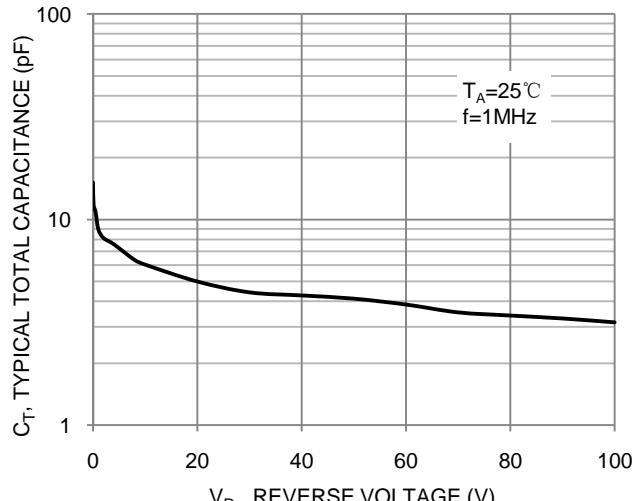
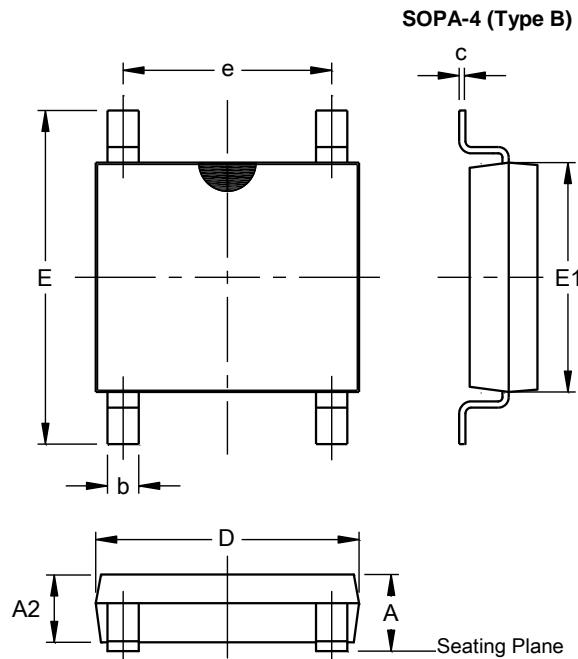


Figure 5. Typical Total Capacitance (Per Element)

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

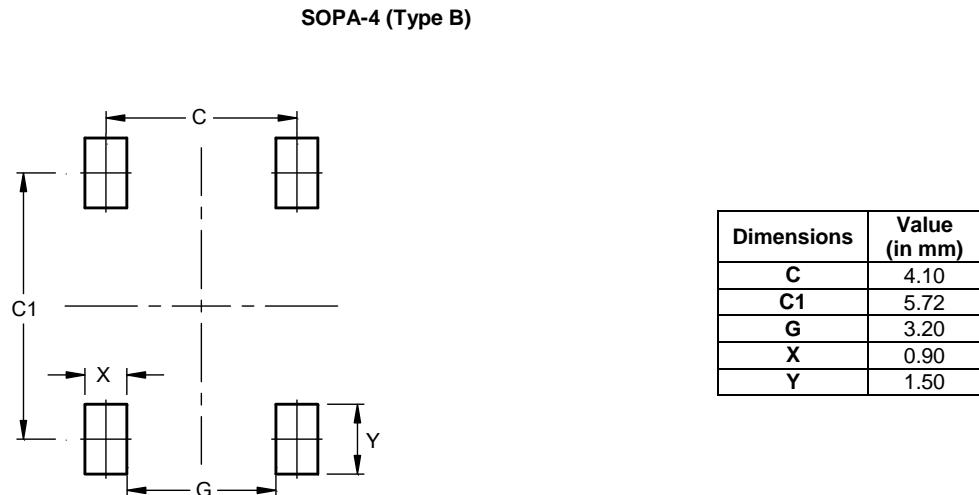


SOPA-4 (Type B)			
Dim	Min	Max	Typ
A	1.15	1.30	--
A2	1.00	1.25	--
b	0.50	0.70	--
c	0.15	0.25	--
D	4.80	5.30	--
E	6.00	6.80	--
E1	4.20	4.60	--
e	3.80	4.20	--

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.



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